

RF NEMS Magnetolectric Sensor Simulation And Demonstration

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Introduction: RF NEMS Magnetolectric (ME) Sensor with a ferromagnetic (FeGaB) / piezoelectric (AlN) thin film heterostructure is simulated, fabricated and measured in this work. To analyze the response of the ME structures, the coupling between the magnetic, elastic and electric field in the two different magnetostrictive and piezoelectric effects should be taken into consideration.

Results: The ME sensors was fabricated using a five-mask CMOS microfabrication process. The RF magnetic field is generated by a RF coil soldered on SMA port and connected to the out-put port of the lock-in amplifier. The simulation of direct ME coupling induced voltage generated by ~ 60 nT_{rms} RF magnetic field was about $118\mu\text{V}$ which was comparable to the experimental results $180\mu\text{V}$ at $\sim 60\text{MHz}$.

Computational Methods:

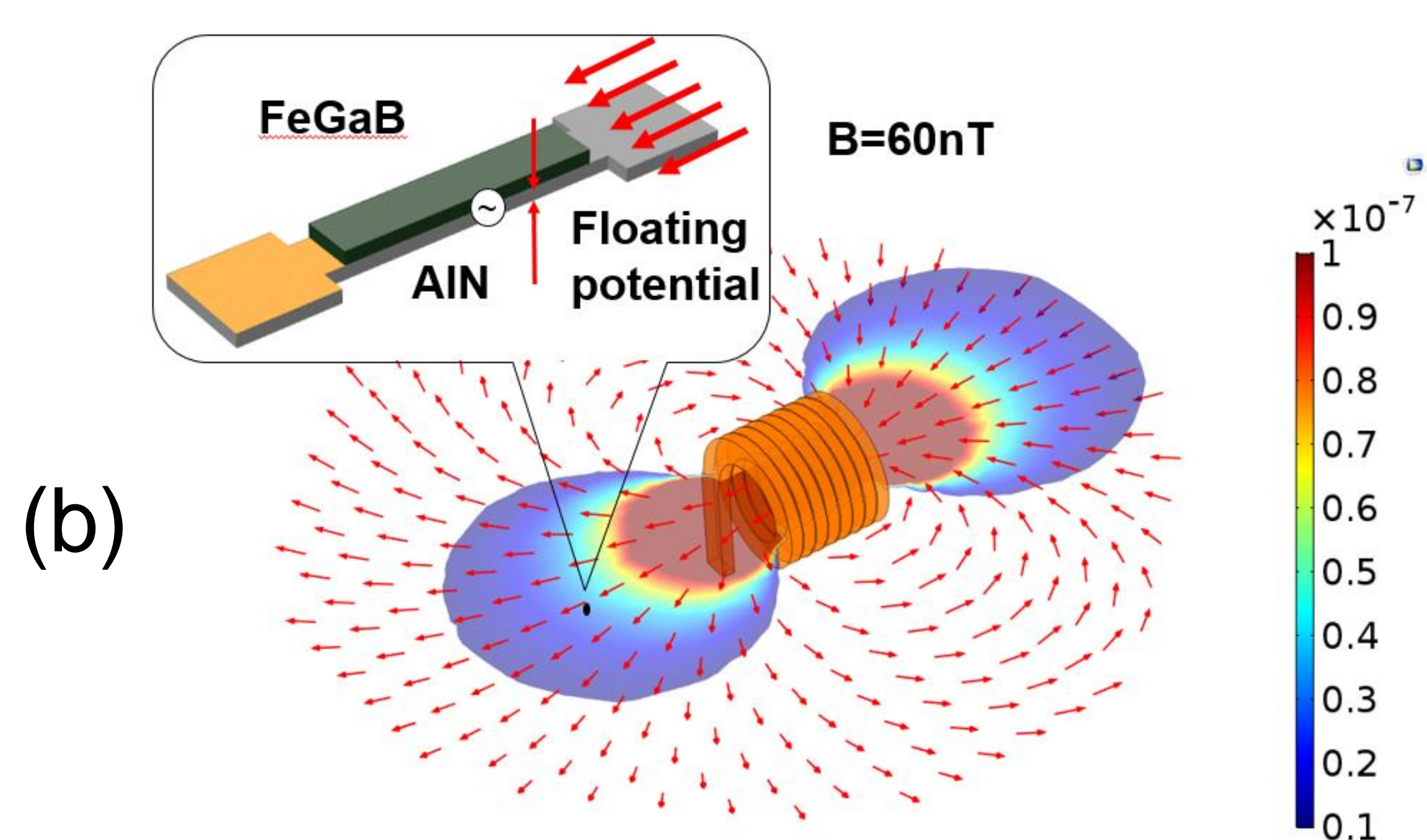
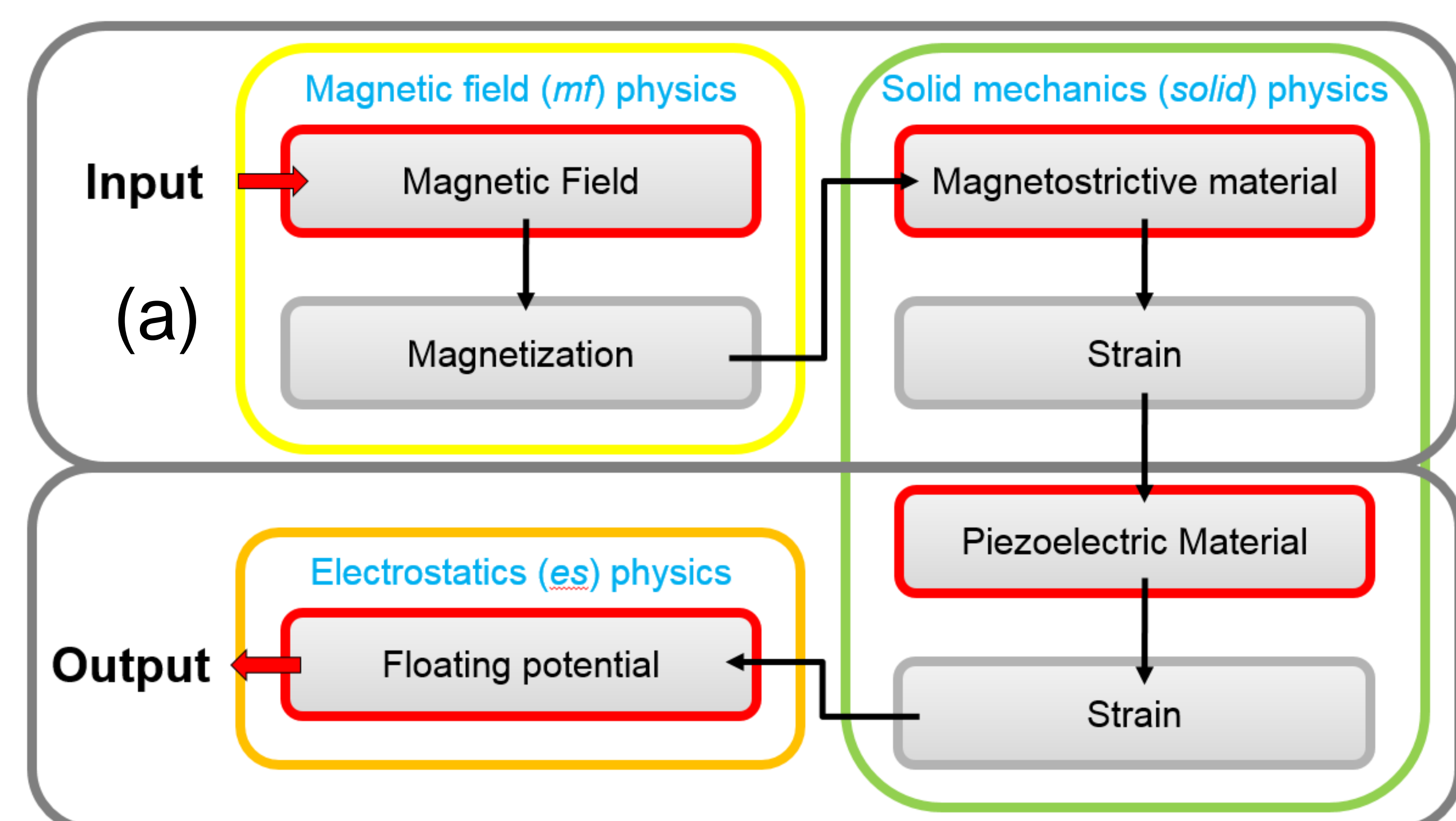


Figure 1. (a) Simulation process flow. Coupling (b) Simulation setup.

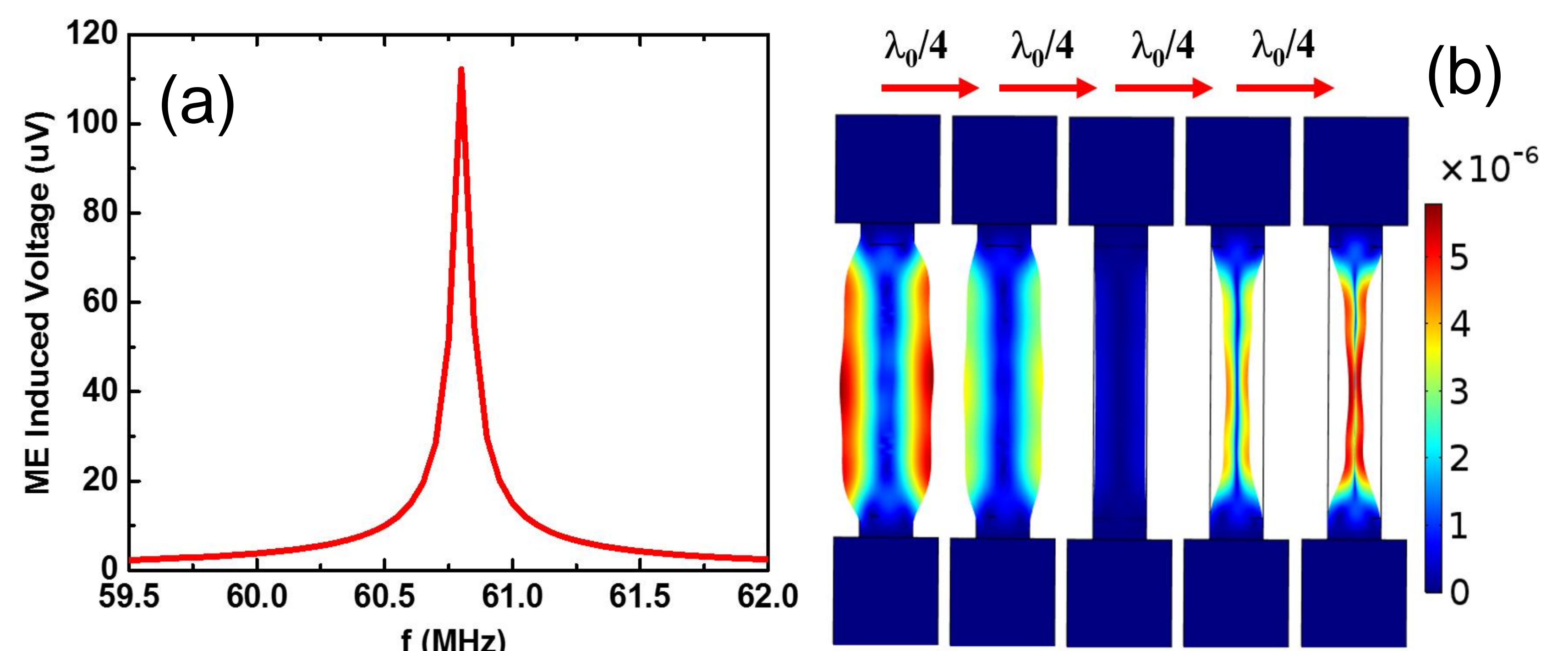


Figure 2. (a) Simulated induced voltage by Direct ME Coupling (b) Displacement profile of the ME resonator.

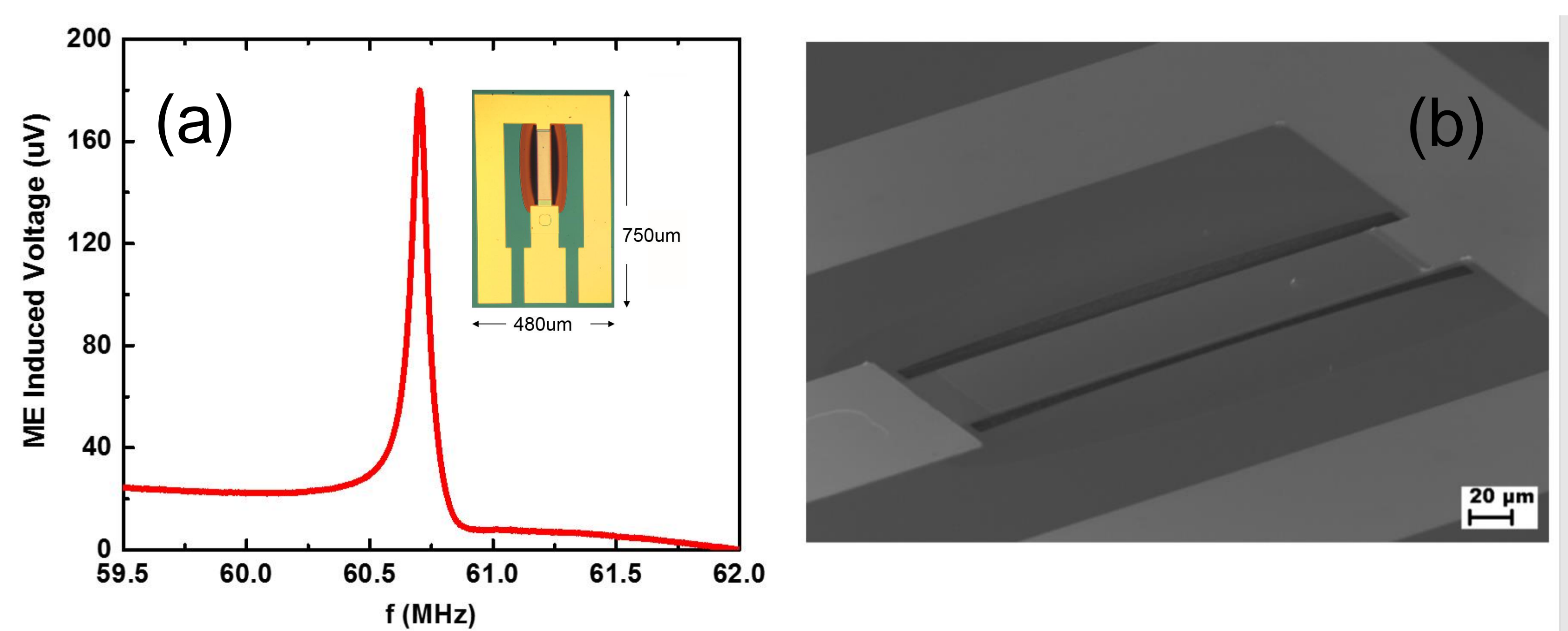


Figure 3. (a) Measured induced voltage by Direct ME Coupling and the optical image (b) SEM of the ME sensor.

Conclusions: The Direct Magnetolectric coupling simulation capability by COMSOL® is expected to have great impacts on our future communication systems for internet of things (IoT), wearable sensors, bio-implantable and bio-injectable sensors, smart phones, wireless communication systems, etc.

References: T. Nan et al., Acoustically actuated ultra-compact NEMS magnetolectric antennas, *Nature Communications*, 8, 296